



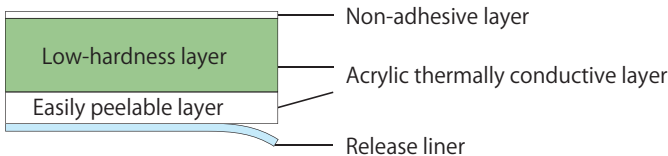
COOLPROVIDE™ / CPVP-30-F



Silicone free, low-hardness, high-thermally conductive pad (3W/m · K)

- The two-layer structured putty can be handled in the same way as a pad.
- has a thermal conductivity of 3.0W/m · K, which is 2.1 times higher than the existing product.
- Silicon free COOLPROVIDE contains no siloxane.
- With excellent flexibility and stress relaxation, the assembled pad can lower the load on heating elements and PCBs.
- Recommended operating temperature: -40~125°C
- bleeds less oil compared with the silicone type.

Cross-section view

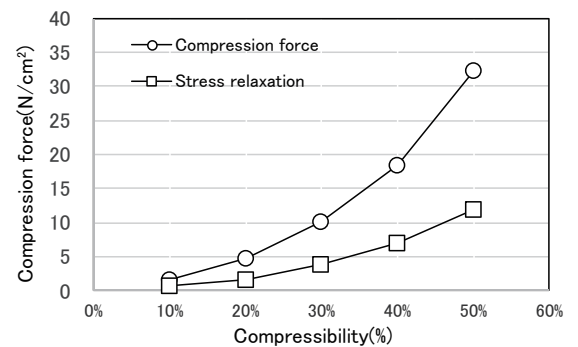


Properties

| Item | Unit | Compliance standard | CPVP-30 |
|-----------------------------------|---------|----------------------------------|--|
| Thickness | mm | — | 1.0/1.5/2.0 ^{※1} , 3.0/4.0 |
| Thermal conductivity | W/m · K | ISO 22007-2 (Hot Disc method) | 3.0 (Low-hardness layer) |
| Hardness | ASKER C | JIS K 7312 | 7 (Low-hardness layer) |
| Volume resistivity | Ω · cm | JIS K 6911 | 1.0 × 10 ¹¹ |
| Flammability | — | UL94 | Equivalent to V-0 |
| Color | — | — | Green/White |
| Recommended operating temperature | °C | — | -40~125 |

※ 1.0, 1.5 and 2.0mm thick products are under development.

Compressive stress relaxation properties



Sample dimensions : □10mm(t=4.0mm)
 Cross-head speed : 1mm/min
 Compression plate materials
 Upper : Stainless steel Φ28mm
 Lower : Gold plated copper Φ106mm

※ Compressive force is the largest load value immediately after compression.

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